

ON Semiconductor®

# FGA25S125P 1250 V, 25 A Shorted-anode IGBT

#### **Features**

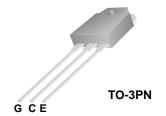
- · High Speed Switching
- Low Saturation Voltage:  $V_{CE(sat)} = 1.8 \text{ V} @ I_{C} = 25 \text{ A}$
- · High Input Impedance
- · RoHS Compliant

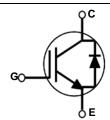
### **Applications**

• Induction Heating, Microwave Oven

## **General Description**

Using advanced field stop trench and shorted-anode technology, ON Semiconductor's shorted-anode trench IGBTs offer superior con-duction and switching performances for soft switching applications. The device can operate in parallel configuration with exceptional avalanche capability . This device is designed for induction heating and microwave oven.





## **Absolute Maximum Ratings**

Symbol	Description		FGA25S125P-SN00337	Unit
V <sub>CES</sub>	Collector to Emitter Voltage		1250	V
V <sub>GES</sub>	Gate to Emitter Voltage		± 25	V
I <sub>C</sub>	Collector Current	@ T <sub>C</sub> = 25°C	50	Α
	Collector Current	@ T <sub>C</sub> = 100°C	25	Α
I <sub>CM (1)</sub>	Pulsed Collector Current		75	Α
I <sub>F</sub>	Diode Continuous Forward Current	@ T <sub>C</sub> = 25°C	50	Α
	Diode Continuous Forward Current	$@ T_C = 100^{\circ}C$	25	Α
P <sub>D</sub>	Maximum Power Dissipation	@ T <sub>C</sub> = 25°C	250	W
	Maximum Power Dissipation	@ T <sub>C</sub> = 100°C	125	W
T <sub>J</sub>	Operating Junction Temperature		-55 to +175	°C
T <sub>stg</sub>	Storage Temperature Range		-55 to +175	°C
T <sub>L</sub>	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds	:	300	°C

### **Thermal Characteristics**

Symbol Parameter		Тур.	Max.	Unit	
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case, Max	-	0.6	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max	-	40	°C/W	

#### Notes:

1: Limited by Tjmax

## **Package Marking and Ordering Information**

<b>Device Marking</b>	Device	Package	Reel Size	Tape Width	Quantity	
FGA25S125P	FGA25S125P -SN00337	TO-3PN	-	-	30	

# Electrical Characteristics of the IGBT $T_C = 25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	teristics					
BV <sub>CES</sub>	Collector to Emitter Breakdown Voltage	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1 mA	1250	-	-	V
$\Delta BV_{CES} \over \Delta T_J$	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0 \text{ V}, I_{C} = 1 \text{ mA}$	-	1.2	-	V/ºC
I <sub>CES</sub>	Collector Cut-Off Current	V <sub>CE</sub> = 1250V, V <sub>GE</sub> = 0V	-	-	1	mA
I <sub>GES</sub>	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$	-	-	±500	nA
On Charac	teristics			•		
V <sub>GE(th)</sub>	G-E Threshold Voltage	I <sub>C</sub> = 25mA, V <sub>CE</sub> = V <sub>GE</sub>	4.5	6.0	7.5	V
V <sub>CE(sat)</sub>	Collector to Emitter Saturation Voltage	$I_C = 25A, V_{GE} = 15V$ $T_C = 25^{\circ}C$	-	1.8	2.35	V
		I <sub>C</sub> = 25A, V <sub>GE</sub> = 15V T <sub>C</sub> = 125°C	-	2.05	-	V
		I <sub>C</sub> = 25A, V <sub>GE</sub> = 15V, T <sub>C</sub> = 175°C	-	2.16	-	V
	Diode Forward Voltage	I <sub>F</sub> = 25A, T <sub>C</sub> = 25°C	-	1.7	2.4	V
$V_{FM}$		I <sub>F</sub> = 25A, T <sub>C</sub> = 175°C	-	2.1	-	V
C <sub>ies</sub>	Input Capacitance	Vor = 30V Vor = 0V	-	2150	-	pF
	Characteristics	I			Γ	
C <sub>oes</sub>	Output Capacitance	$V_{CE} = 30V, V_{GE} = 0V,$	-	48	-	pF
C <sub>res</sub>	Reverse Transfer Capacitance	f = 1MHz	-	36	-	pF
Switching	Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time		-	24	-	ns
t <sub>r</sub>	Rise Time		-	250	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 600V, I_{C} = 25A,$	-	502	-	ns
t <sub>f</sub>	Fall Time	$R_G = 10\Omega$ , $V_{GE} = 15V$ ,	-	138	-	ns
E <sub>on</sub>	Turn-On Switching Loss	Resistive Load, T <sub>C</sub> = 25°C	-	1085	-	uJ
E <sub>off</sub>	Turn-Off Switching Loss		-	580	-	uJ
E <sub>ts</sub>	Total Switching Loss		-	1665	-	uJ
			+	21.2	-	ns
t <sub>d(on)</sub>	Turn-On Delay Time		-	21.2		
	Turn-On Delay Time Rise Time		-	304	-	ns
t <sub>r</sub>		Voc = 600V lo = 25A	-		-	ns ns
t <sub>r</sub>	Rise Time	$V_{CC} = 600V, I_{C} = 25A,$ $R_{G} = 10\Omega, V_{GE} = 15V,$		304		
t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub>	Rise Time Turn-Off Delay Time		-	304 490	-	ns
t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub> E <sub>on</sub>	Rise Time Turn-Off Delay Time Fall Time	$R_G = 10\Omega$ , $V_{GE} = 15V$ ,	-	304 490 232	-	ns ns
$t_r$ $t_{d(off)}$ $t_f$ $E_{on}$	Rise Time Turn-Off Delay Time Fall Time Turn-On Switching Loss Turn-Off Switching Loss	$R_G = 10\Omega$ , $V_{GE} = 15V$ ,	-	304 490 232 1310		ns ns uJ
$t_r$ $t_{d(off)}$ $t_f$ $E_{on}$ $E_{off}$	Rise Time Turn-Off Delay Time Fall Time Turn-On Switching Loss Turn-Off Switching Loss Total Switching Loss	$R_G = 10\Omega$ , $V_{GE} = 15V$ ,	-	304 490 232 1310 952		ns ns uJ
t <sub>d(on)</sub> t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub> E <sub>on</sub> E <sub>off</sub> E <sub>ts</sub> Q <sub>g</sub>	Rise Time Turn-Off Delay Time Fall Time Turn-On Switching Loss Turn-Off Switching Loss	$R_G = 10\Omega$ , $V_{GE} = 15V$ ,		304 490 232 1310 952 2262	- - -	ns ns uJ uJ

**Figure 1. Typical Output Characteristics** 

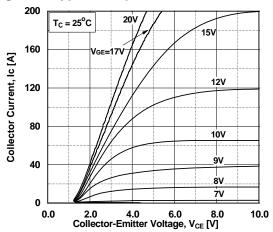


Figure 3. Typical Saturation Voltage Characteristics

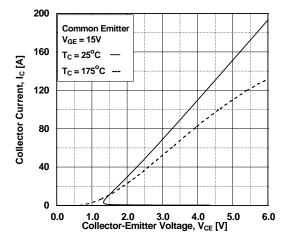
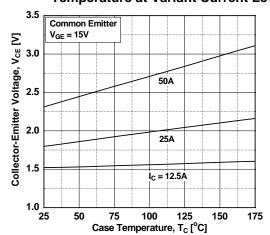


Figure 5. Saturation Voltage vs. Case
Temperature at Variant Current Level



**Figure 2. Typical Output Characteristics** 

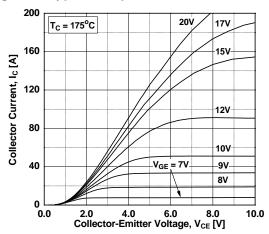


Figure 4. Transfer Characteristics

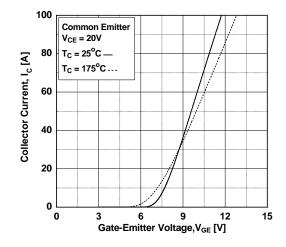


Figure 6. Saturation Voltage vs. V<sub>GE</sub>

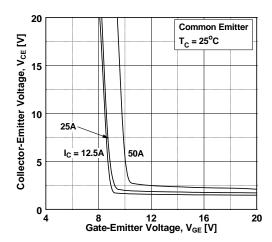


Figure 7. Saturation Voltage vs. V<sub>GE</sub>

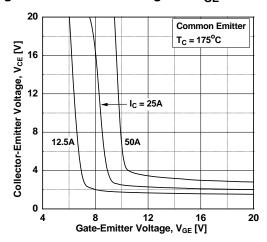


Figure 9. Gate charge Characteristics

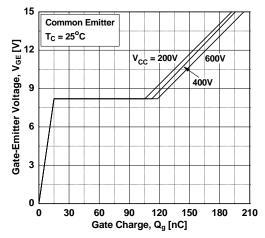
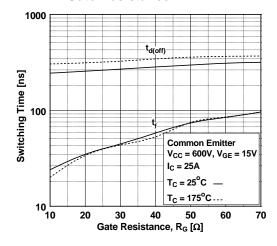


Figure 11. Turn-on Characteristics vs.
Gate Resistance



**Figure 8. Capacitance Characteristics** 

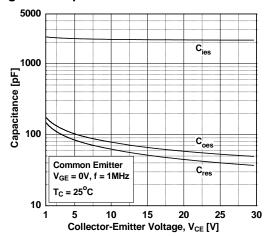


Figure 10. SOA Characteristics

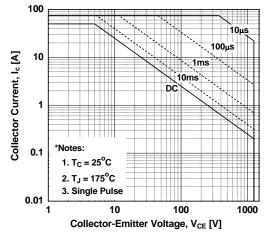


Figure 12. Turn-off Characteristics vs.
Gate Resistance

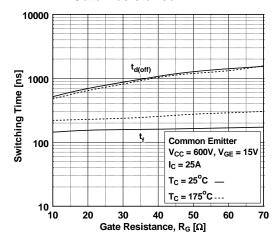


Figure 13. Turn-on Characteristics vs. Collector Current

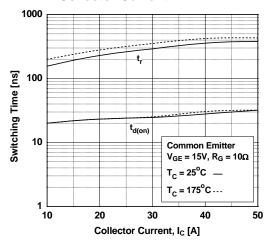


Figure 15. Switching Loss vs.

Gate Resistance

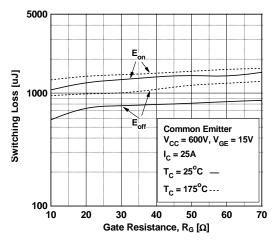


Figure 17. Turn off Switching SOA Characteristics

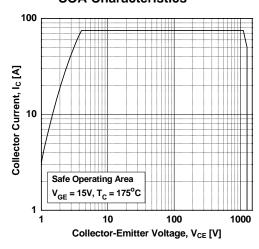


Figure 14. Turn-off Characteristics vs.
Collector Current

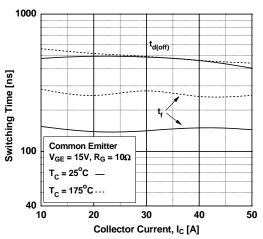


Figure 16. Switching Loss vs. Collector Current

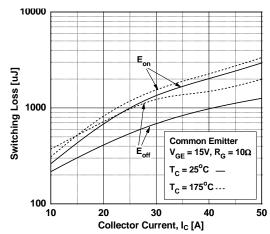


Figure 18. Forward Characteristics

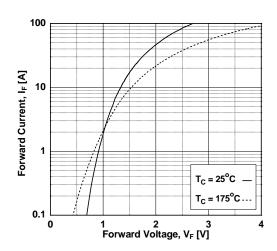
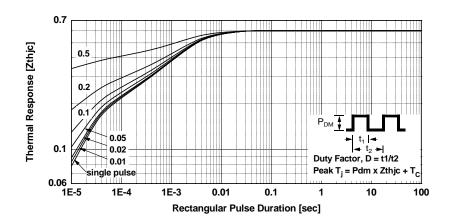


Figure 19. Transient Thermal Impedance of IGBT



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